

In re Application  
Serial No.Michio Asahina  
07/780,455

Date: March 31, 1993

Filed:

October 22, 1991

For:

SEMICONDUCTOR DEVICE

COMMISSIONER OF PATENTS AND TRADEMARKS  
Washington, D.C. 20231

Sir:

Transmitted herewith is an amendment/response in the above-identified application.

☐ Small entity status of this application under 37 CFR 1.9 and 1.27 has been established by a verified statement previously submitted.☐ A verified statement to establish small entity status under 37 CFR 1.9 and 1.27 is enclosed.☒ No additional fee is required.☐ Information Disclosure Statement

The fee has been calculated as shown below:

	(Col. 1) CLAIMS REMAINING AFTER AMENDMENT	(Col. 2) HIGHEST NO. PREVIOUSLY PAID FOR	(Col. 3) SMALL PRESENT EXTRA RATE	SMALL ENTITY ADDIT. FEE OR RATE	OTHER THAN A SMALL ENTITY ADDIT. FEE
TOTAL	* 3 MINUS ** 24	= 0	x11	\$ OR	x22 \$
INDEP CLAIMS	* 3 MINUS *** 4	= 0	x37	\$ OR	x74 \$
FIRST PRESENTATION OF MULTIPLE DEP. CLAIM			+115	\$ OR	+230 \$
		TOTAL		\$ OR	TOTAL \$ 0

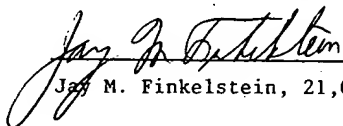
\* If the entry in Col. 1 is less than the entry in Col. 2, write "0" in Col. 3.

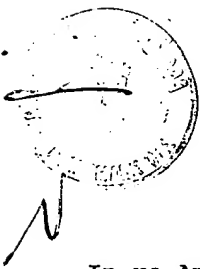
\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 20, write "20" in this space.

\*\*\* If the "Highest Number Previously Paid For" IN THIS SPACE is less than 3, write "3" in this space. The "Highest Number Previously Paid For" (Total or Independent) is the highest number found from the equivalent box on Col. 1 of a prior amendment or the number of claims originally filed.

☐ Please charge my Deposit Account No. 19-3725 the amount of \$\_\_\_\_\_. A duplicate copy of this sheet is enclosed.☐ A check in the amount of \$\_\_\_\_\_ to cover the extension fee is enclosed.☐ A check in the amount of \$\_\_\_\_\_ to cover the filing fee is enclosed.☐ A check in the amount of \$200.00 to cover the Information Disclosure Statement.☐ A check in the amount of \$130.00 to cover the Information Disclosure Statement.☒ The Commissioner is hereby authorized to charge payment of the following fees associated with this communication or credit any overpayment to Deposit Account No. 19-3725. A duplicate copy of this sheet is enclosed.☒ Any filing fees under 37 CFR 1.16 for the presentation of extra claims.☒ Any patent application processing fees under 37 CFR 1.17.

Respectfully submitted,


  
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PATENT  
PD-8811FWC

37/G  
4/9/93  
AP

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of )  
MICHIO ASAHINA ) ART GROUP UNIT: 2508  
Serial No.: 07/780,455 ) EXAMINER: S. Loke  
Filing Date: October 22, 1991 )  
For: SEMICONDUCTOR DEVICE )

AMENDMENT UNDER 37 C.F.R. § 1.116

Honorable Commissioner of  
Patents & Trademarks  
Washington, D.C. 20231

APR 08 1993  
RECEIVED

Dear Sir:

In response to the Examiner's Action dated January 4, 1993,  
kindly amend the above-identified application as follows:

IN THE CLAIMS:

Kindly cancel claim 26 and amend claim 25 as follows:

25. (AMENDED) A method of fabricating a semiconductor device, comprising the steps of:  
providing a substrate having a doped semiconductor region, and a gate wiring, forming a lower conductor structure, and forming an insulating layer overlying said lower structure, and having at least one through opening extending to said lower conductor structure; and  
forming an upper conductor structure on the insulating layer and causing the upper conductor structure to be connected to the lower conductor structure via the through opening;

*and contacting the metal plating layer*  
*which includes a metal plating layer*  
*and contacting the metal plating layer*  
*which also includes a metal plating layer*

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